Laird
Smart Technology. Delivered.

SNK55-RXP
Form-In-Place



* does not represent actual color

SNK55-RXP Form-In-Place

A rapid-cure, silver/copper-filled silicone elastomer Form-In-Place gasket material.

Laird Technologies introduces its newest line of FIP products—EMI Sentry. These Form-In-Place pastes are extremely fast curing with reliable shielding effectiveness and strength.

Laird Technologies' Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for basestations, PDAs, PC cards, radios, mobile phones, as well as many other cast or plastic enclosures and packaged electronic assemblies.

TYPICAL VALUES

	TEST METHOD	UNITS	SNK55-RXP
Elastomer			Silicone
Filler			Silver/Copper
ELECTRICAL PROPERTIES			
Volume Resistivity		ohm-cm	0.002
Shielding Effectiveness	MIL-DTL-83528C		
200 MHz to 10 GHz	Para. 4.5.12	dB	>90
PHYSICAL PROPERTIES			
Hardness	ASTM D2240	Shore A	55
Tensile Strength	ASTM D412	kPa	1300
Tensile Elongation	ASTM D412	%	300
Density (cured)	ASTM D792	g/cm^3	3.0
Density (uncured)	LT-FIP-CLE-09	g/cm^3	2.3
Compression Set	ASTM D395	%	10
Adhesion Strength (Al)	LT-FIP-CLE-03	N/cm^2	200
Compression-Deflection (a)	LT-FIP-CLE-07		
at 20% compression		lb/in	1.2
at 40% compression		lb/in	5.2
Temperature Range		°C	-50°C to 100°C
UL rating	UL-94		V0
CURING REQUIREMENTS			
Cure Conditions	15°C to 40°C, 50% relative humidity		
At 22°C and 50% RH	LT-FIP-CLE-14		
Time before handling			1 hour
Full Cure			24 hours

(a) Compression-deflection bead size 0.60 mm (H) x 0.70 mm (W)

rev. 07/02/09

EMI SENTRY™

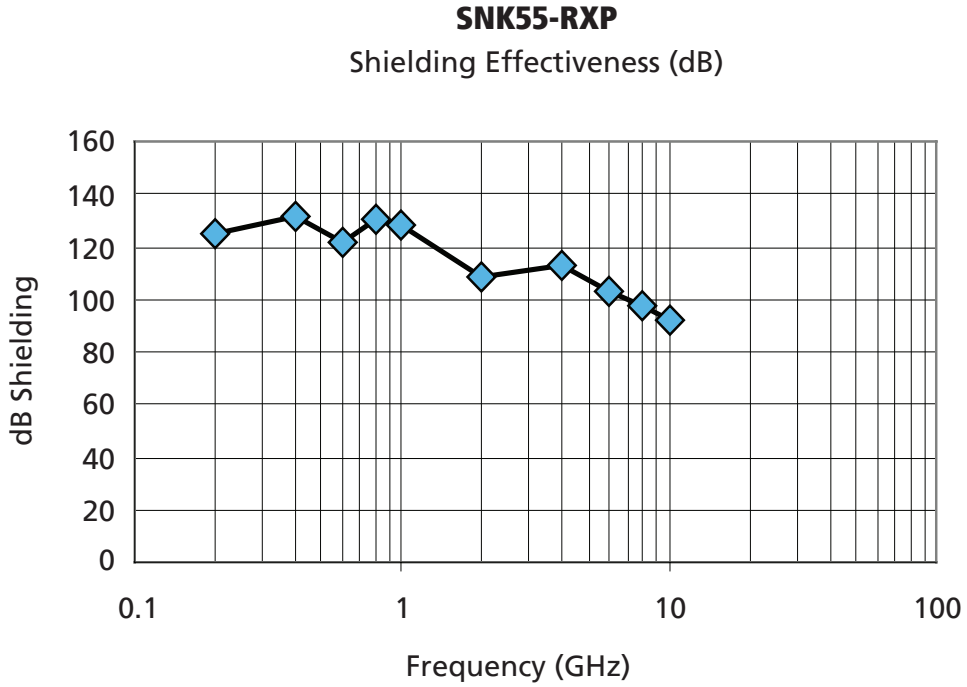
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SNK55-RXP Form-In-Place

A rapid-cure, silver/copper-filled silicone elastomer Form-In-Place gasket material.

The SNK55-RXP has remarkable shielding effectiveness and is room temperature cured. Products in the EMI Sentry line all have superior adhesion strength, strong reliability in low compression sets, as well as heat and humidity resistance.



EMI SENTRY™

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